

## Amendment to the Claims

1-11. (Cancelled)

12. (Previously Presented) A method for removing semiconductor chip in which one out of a plurality of semiconductor chips formed from a diced semiconductor wafer is removed from a pressure-sensitive adhesive sheet, which holds the semiconductor chips by adhering thereto, so that the semiconductor chip is extracted from the adhesive sheet, the method comprising:

bringing a plurality of protruding portions on a first contact surface of a removing member into contact with a bottom surface of the semiconductor chip through the adhesive sheet at a region on a bottom surface side of the adhesive sheet while sucking and holding a vicinity of the bottom surface-side region of the adhesive sheet corresponding to an adhesion region of the semiconductor chip by a second contact surface of a holding portion located around the first contact surface;

sucking the adhesive sheet in between the respective protruding portions so as to partially remove the adhesive sheet in the adhesion region from the semiconductor chip at suction positions; and

moving respective contact positions with the protruding portions to the suction positions on the bottom surface-side region of the adhesive sheet by moving the removing member along the bottom surface of the semiconductor chip relative to the holding portion, in a condition in which the ~~that the~~ first contact surface is located at an almost same height of the second contact surface, so that a region of the partial removal in the adhesion region is made to expand.

13. **(Currently Amended)** The method for removing semiconductor chip as defined in Claim 12, wherein a force for sucking and holding~~to suck and hold~~ the vicinity of the bottom surface-region of the adhesive sheet corresponding to the adhesion region is set to be larger than a force for sucking~~to suck~~ the adhesive sheet in between the respective protruding portions.

14. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a reciprocal movement of the removing member in a specified direction along the bottom surface of the semiconductor chip.

15. **(Currently Amended)** The method for removing semiconductor chip as defined in Claim 14, wherein an amplitude of the~~in the~~ reciprocal movement of the removing member is larger than a formation interval of the respective protruding portions.

16. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a rotating movement of the removing member around a direction almost perpendicular to the bottom surface of the semiconductor chip.

17. **(Cancelled)**

18. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a reciprocal movement of the removing

member in a specified direction with a specified amplitude along the bottom surface of the semiconductor chip.

19. **(Cancelled)**

20. **(New)** The method for removing semiconductor chip as defined in Claim 13, wherein the force for sucking and holding the vicinity of the bottom surface-region of the adhesive sheet corresponding to the adhesion region is controlled by a first valve, and the force for sucking the adhesive sheet in between the respective protruding portions is controlled by a second valve.